

## ■ Features

- 1608 (0603) size, compact and high intensity reflector type

## ■ Outline

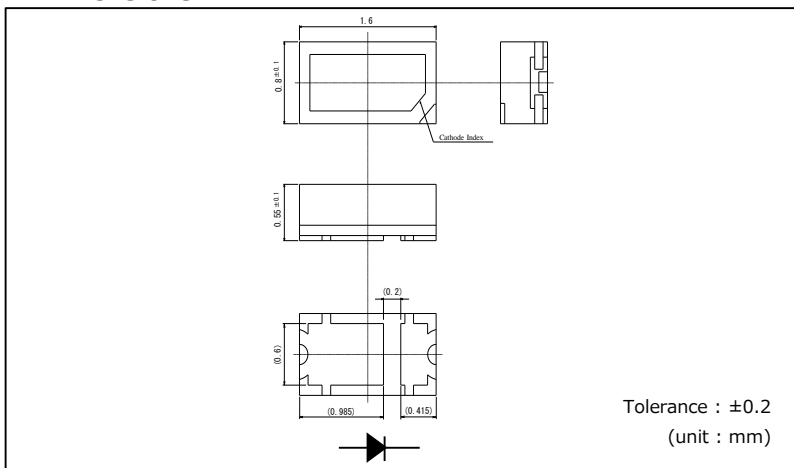


## ■ Size

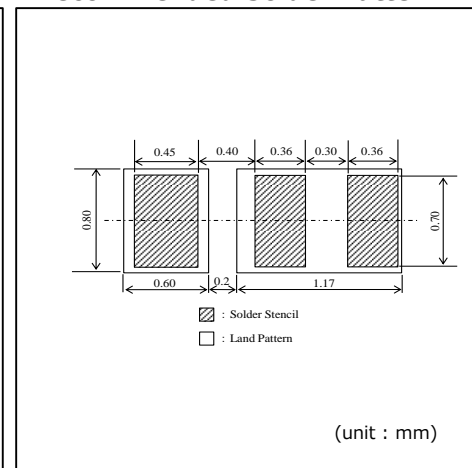
1608 (0603)  
1.6 × 0.8mm (t=0.55mm)

Color  
Type **WB**

## ■ Dimensions



## ■ Recommended Solder Pattern



## ■ Moisture sensitivity level(MSL) : Level 3

## ■ Specifications

Part No.	Chip Structure	Emitting  Color	Absolute Maximum Ratings (Ta=25°C)						Electrical and Optical Characteristics (Ta=25°C)										
			Power	Forward	Peak Forward	Reverse	Operating Temp.	Storage Temp.	Forward Voltage V <sub>F</sub>		Reverse Current I <sub>R</sub>		Chromaticity		Luminous Intensity I <sub>V</sub>			Luminous Intensity I <sub>V</sub>	
			Dissipation	Current	Current	Voltage			Typ.	I <sub>F</sub>	Max.	V <sub>R</sub>	(x,y)	I <sub>F</sub>	Min.	Typ.	I <sub>F</sub>	Typ.	I <sub>F</sub>
			P <sub>D</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> (mA)	V <sub>R</sub> (V)	T <sub>opr</sub> (°C)	T <sub>stg</sub> (°C)	(V)	(mA)	(μA)	(V)	(mA)	(cd)	(cd)	(mA)	(lm)	(mA)	
□ CSL1104WBx Series	InGaN	White	144	40	100*1	5	-40~+110	-40~+110	2.9	20	10	5	(0.281, 0.275)	20	(1400)	2200	(2800)	20	

\*1 : Duty 1/10, 1kHz ( ) : Reference

# ■ Electrical Characteristics Curves

Reference

Fig.1 Forward Current  
- Forward Voltages

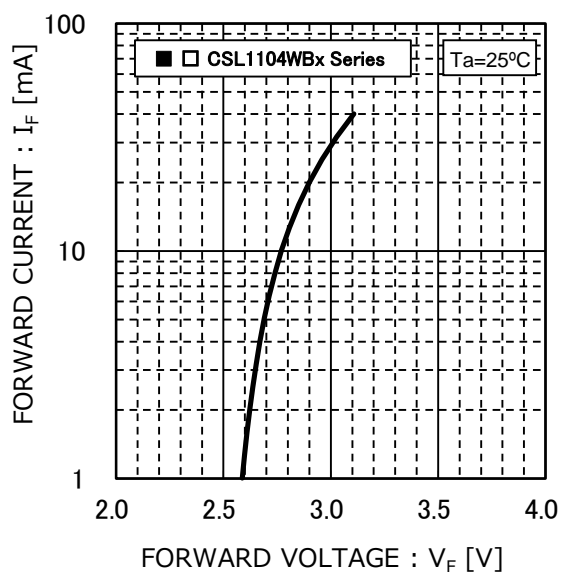


Fig.2 Luminous Intensity -  
Atmosphere Temperature

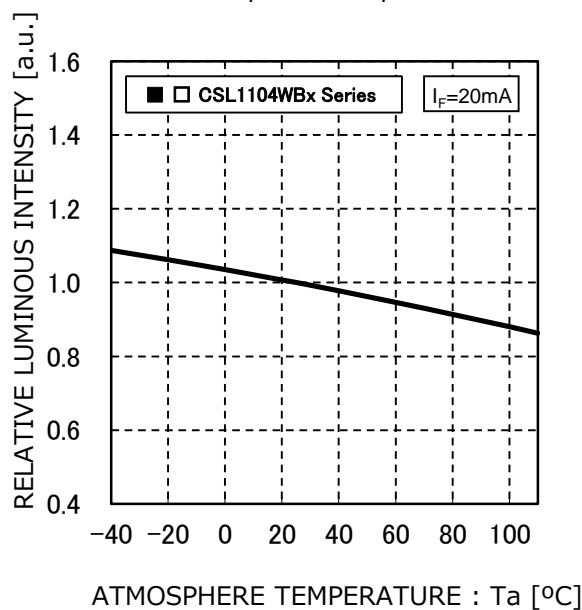


Fig.3 Luminous Intensity - Forward Current

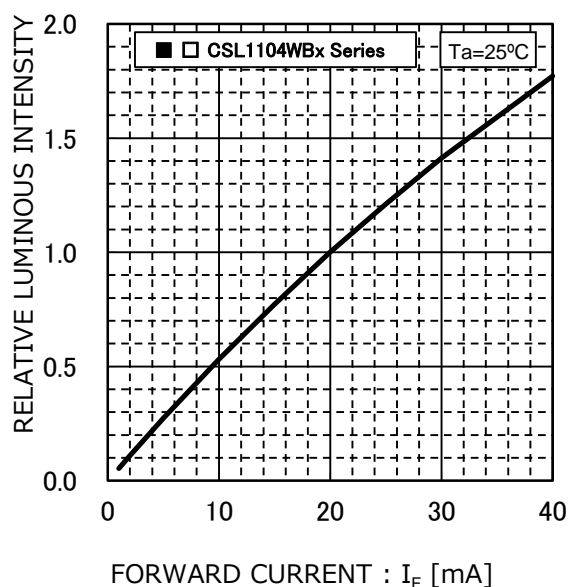
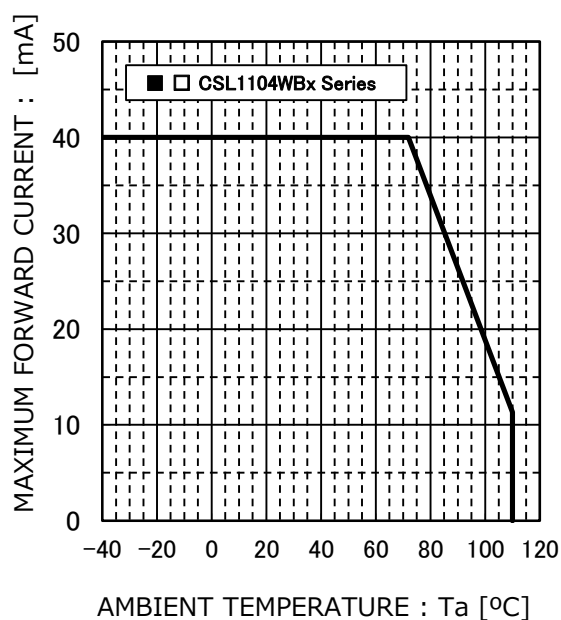
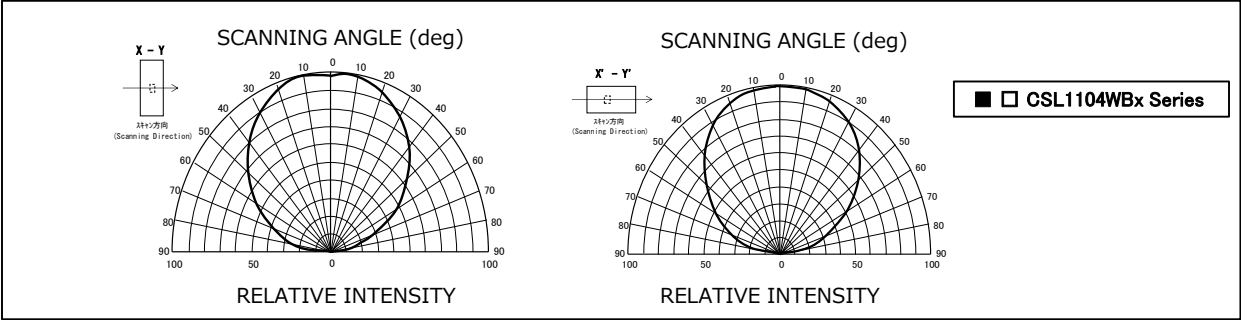


Fig.4 Derating



■ Viewing Angle

Reference



## ■ Rank Reference of Brightness\*

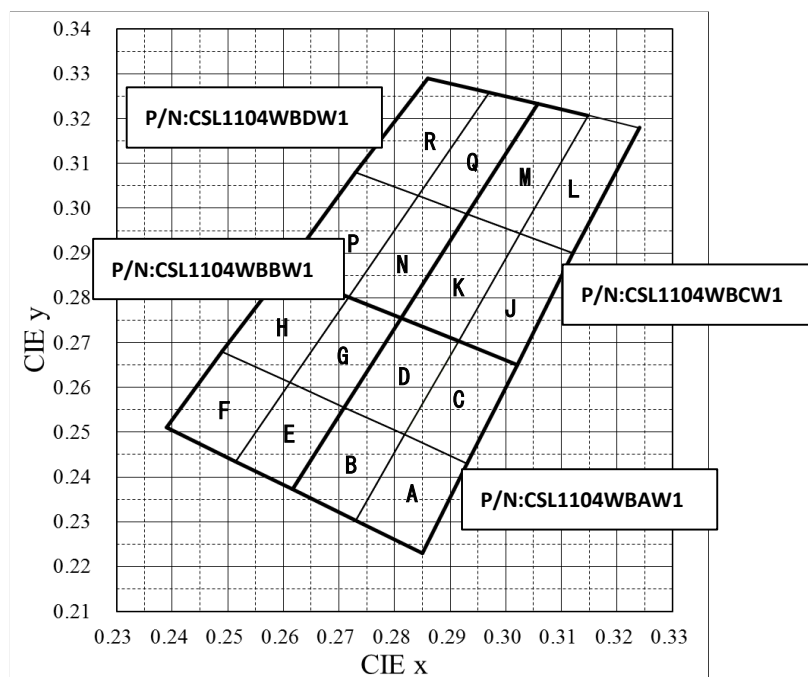
\*Measurement tolerance:  $\pm 10\%$ 

White(WB)

(Ta=25°C, If=20mA)

Rank	R1	R2	S1	S2	T1	T2	U1	U2	V1	V2	W1	W2	X1	X2	Y1	Y2	Z1	Z2
Iv(cd)	56~71	71~90	90~110	110~140	140~180	180~220	220~280	280~360	360~450	450~560	560~710	710~900	900~1100	1100~1400	1400~1800	1800~2200	2200~2800	2800~3600
CSL1104WBx Series																		

## ■ Chromaticity Diagram



(T a = 25°C, If=20mA)

Chromaticity  
rank

A		B		C		D	
x	y	x	y	x	y	x	y
0.285	0.223	0.273	0.230	0.293	0.243	0.282	0.249
0.273	0.230	0.262	0.237	0.282	0.249	0.271	0.256
0.282	0.249	0.271	0.256	0.292	0.270	0.281	0.275
0.293	0.243	0.282	0.249	0.302	0.265	0.292	0.270

Chromaticity  
rank

E		F		G		H	
x	y	x	y	x	y	x	y
0.262	0.237	0.251	0.243	0.271	0.256	0.261	0.261
0.251	0.243	0.239	0.251	0.261	0.261	0.249	0.268
0.261	0.261	0.249	0.268	0.272	0.280	0.260	0.286
0.271	0.256	0.261	0.261	0.281	0.275	0.272	0.280

Chromaticity  
rank

J		K		L		M	
x	y	x	y	x	y	x	y
0.302	0.265	0.292	0.270	0.312	0.290	0.303	0.294
0.292	0.270	0.281	0.275	0.303	0.294	0.293	0.299
0.303	0.294	0.293	0.299	0.315	0.321	0.306	0.323
0.312	0.290	0.303	0.294	0.324	0.318	0.315	0.321

Chromaticity  
rank

N		P		Q		R	
x	y	x	y	x	y	x	y
0.281	0.275	0.272	0.280	0.293	0.299	0.284	0.303
0.272	0.280	0.260	0.286	0.284	0.303	0.273	0.308
0.284	0.303	0.273	0.308	0.297	0.326	0.286	0.329
0.293	0.299	0.284	0.303	0.306	0.323	0.297	0.326

Tolerance:  $\pm 0.01$

(1)

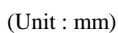
Technical drawing showing a side view and a cross-sectional view of a mechanical component.

**Side View Dimensions:**

- Total Length: 8.0
- Distance between first two holes: 4.0
- Hole Diameter:  $\phi 1.55$
- Distance from right end to center of last hole: 1.75
- Distance from right end to center of second-to-last hole: 3.5
- Distance from right end to center of third-to-last hole: 5.5
- Distance from right end to center of fourth-to-last hole: 6.5
- Distance from right end to center of fifth-to-last hole: 7.5
- Distance from right end to center of sixth-to-last hole: 8.0

**Cross-Sectional View Dimensions:**

- Width: 0.73
- Height: 1.94
- Fillet Radius: R1.0



(Note) Tolerance is within  $\pm 0.2\text{mm}$  unless otherwise specified.

The diagram illustrates the structure of a 12-digit LED code. The code is divided into five sections: Series name (2 digits), Package Type (2 digits), Chip type (2 digits), Emitting Color (2 digits), and Resin Color Taping Specification (4 digits). The last four digits are further categorized as Chromaticity rank (for white LED) and Rank sign (Brightness Rank)\*.

**Example Code: CSL1104WBAW1**

- Series name:** CSL (Chip LED)
- Package Type:** 07 (2.9x2.5 t=3.1mm), 09 (1.6x0.8 t=1.24mm), 11 (1.6x0.8 t=0.55mm)
- Chip type:** 11
- Emitting Color:** SB (Sapphire blue), WB (White)
- Resin Color Taping Specification:** T (Transparent Colorless), W (Milky White), U (Unspecify)

- \*Concerning the Brightness rank.
- \*Please refer to the rank chart above for luminous intensity classification.
- \*Part name is individual for each rank.
- \*When shipped as sample,the part name will be a representative part name.

General products are free of ranks.  
Please contact sales if rank appointment is needed.

Complying with IPC/JEDEC J-STD-033.

**■ Precaution (Surface Mount Device)****1. Storage**

If the product is heated during the reflow under the condition of hygroscopic state, it may vaporize and expand which will influence the performance of the product. Therefore, the package is waterproof. Please use the product following the conditions:

**•Using Conditions**

Classification	Temperature	Humidity	Expiration Date	Remark
① Before using	5~30℃	30~70%RH	Within 1 year from Receiving	Storage with waterproof package
② After opening package	5~30℃	Below 70%RH	Within 168h	Please storing in the airtight container with our desiccant (silica gel)

**•Baking**

Bake the product in case of below:

- ① The expiration date is passed.
- ② The color of 5% and 10% on humidity indicator card is not green.  
(Even if the product is before expiration date.)

**•Baking Conditions**

Temperature	Time	Humidity
60±3℃	40~48h	Below 20%RH
Remark	<ul style="list-style-type: none"> <li>• Bake products in reel.</li> <li>• Reel and embossed tape are easy to be deformed when baking, so please try not to apply stress on it.</li> <li>• Recommend bake once.</li> </ul>	

**2. Application Methods****2 – 1. Precaution for Drive System and Off Mode**

Design the circuit without the electric load exceeding the ABSOLUTE MAXIMUM RATING that applies on the products. If drive by constant voltage, it may cause current deviation of the LED and result in deviation of luminous intensity, so we recommend to drive by constant current.

(Deviation of VF Value will cause deviation of current in LED.) Furthermore, for off mode, please do not apply voltage neither forward nor reverse. Especially, for the products with the Ag-paste used in the die bonding, there's high possibility to cause electro migration and result in function failure.

**2 – 2. About Derating**

It is considered that derating characteristics will not result in LED chip's electrical destruction. Even within the derating, the reliability and luminous life can be affected depending on operating conditions and ambient environment. So we would be appreciate it if you can confirm with your application again.

**2 – 3. About product life**

Depending on operating conditions and environment(applied current, ambient temperature and humidity, corrosive gas), decreasing of luminosity and change of chromaticity may occur even within the specification conditions.

Please contact our sales office if you use it for the following applications.

- ① It requires long luminosity life
- ② It is always lit

**2 – 4. Applied Stress on Product**

The top of the LED is very soft, which the silicon resin is used as sealing resin.

Therefore, please pay attention to the overstress on it which may influence its reliability.

**2 – 5. Usage**

The Product is LED. We are not responsible for the usage as the diode such as Protection Chip, Rectifier, Switching and so on.

### 3. Others

#### 3 – 1. Surrounding Gas

Notice that if it is stored under the condition of acid gas (chlorine gas, sulfured gas) or alkali gas (ammonia), it may result in low soldering ability (caused by the change in quality of the plating surface ) or optical characteristics changes (light intensity, chrominance) and change in quality of cause die bonding (Ag-paste) materials. All of the above will function failure of the products.

Therefore, please pay attention to the storage environment for mounted product (concern the generated gas of the surrounding parts of the products and the atmospheric environment).

#### 3 – 2. Electrostatic Damage

The product is part of semiconductor and electrostatic sensitive, there's high possibility to be damaged by the electrostatic discharge. Please take appropriate measures to avoid the static electricity from human body and earthing of production equipment. Especially, InGaN type LEDs have lower resistance value of electrostatic discharge and it is recommended to introduce the ESD protection circuit.

The resistance values of electrostatic discharge (actual values) vary with products, therefore, please call our Sales staffs for inquiries.

#### 3 – 3. Electromagnetic Wave

Applications with strong electromagnetic wave such as, IH cooker, will influence the reliability of LED, therefore please evaluate before using it.

#### 4. Mounting

##### 4 - 1. Soldering

- No resin hardening agent such as filler is used in the sealing resin of the product. Therefore, resin expansion and moisture absorption at humidity will cause heat stress during soldering process and finally has bad influence on the product's reliability.
  - The product is not guaranteed for flow soldering.
  - Do not expose the product in the environment of high temperature (over 100°C) or rapid temperature shift (within 3°C/sec. of temperature gradient) during the flow soldering of surrounding parts.
- In case of carrying out flow soldering of surrounding parts without recommended conditions, please contact us for inquiries.
- Please set appropriate reflow temperature based on our product usage conditions and specification.
  - The max for reflowing is 2 times, please finish the second reflow soldering and flow soldering with other parts within the usage limitation after open the moistureproof package.
  - Compare with N2 reflow, during air reflow, because of the heat and surrounding conditions, it may cause the discoloration of the resin.
  - For our product that has no solder resist, because of its solder amount and soldering conditions, one of its specific characteristics is that solder will penetrate into LED. Thus, there's high possibility that will influence its reliability. Therefore, please be informed, concerning it before using it.

##### 4 - 2. Automatic Mounting

###### 4 - 2 - 1. Suction nozzle

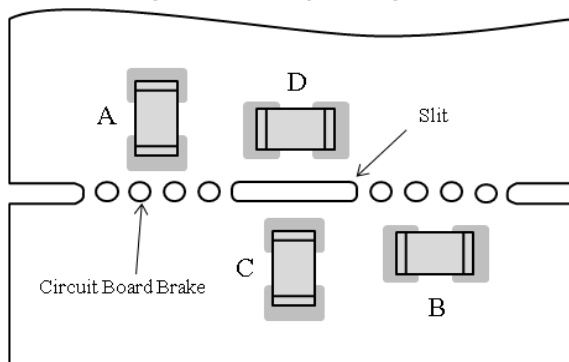
Excessive load may cause damage inside the LED product, so select an optimal suction nozzle according to the material and shape of the LED product.

###### 4 - 2 - 2. Mini Package (Smaller than 1608 size)

- Vibration may result in low mounting rate since it will cause the static electricity of product and adhere to top cover tape. Therefore, the magnet should be set on parts feeder cassette of the mounter to control the product stabilization. In addition, it is recommended to set ionizer to prevent electrostatic charge.

##### 4 - 3. Mounting Location

The stress like bending stress of circuit board dividing after mounting, may cause LED package crack or damage of LED internal junction, therefore, please concern the mounting direction and position to avoid bending or screwing with great stress of the circuit board.



Stress strength according to the mounting position:  
A > B > C > D

##### 4 - 4. Mechanical Stress after Mounting

The mechanical stress may damage the LED after Circuit Mounting, so please pay attention to the touch on product.

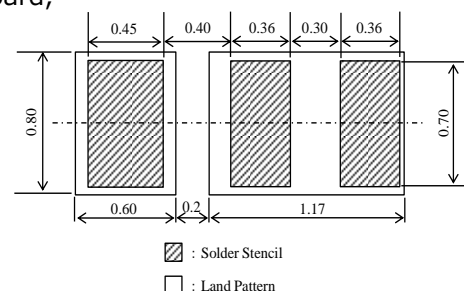
##### 4 - 5. Soldering Pattern for Recommendation

We recommend the soldering pattern that shows on the right. It will be different according to mounting situation of circuit board, therefore, please concern before designing.

※The product has adopted the electrode structure that it should solder with back electrode of the product.

Thus, please be informed that the shape of electrode pin of solder fillet formation is not guaranteed.

The through hole on electrode surface is for conduction of front and rear electrodes but not for formation of solder fillet.



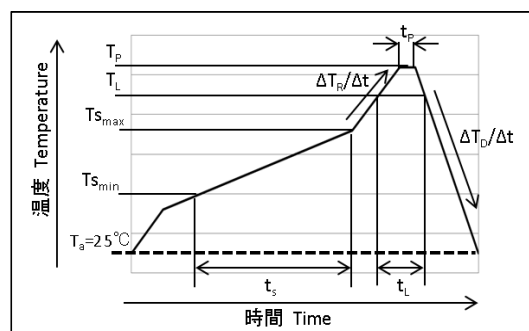


#### 4 – 6. Reflow Profile

For reflow profile, please refer to the conditions below:(※)

##### ■ Meaning of marks, Conditions

Mark	Meanings	Conditions
$T_{S_{max}}$	Maximum of pre-heating temperature	180℃
$T_{S_{min}}$	Minimum of pre-heating temperature	140℃
$t_s$	Time from $T_{S_{min}}$ to $T_{S_{max}}$	Over 60sec.
$T_L$	Reference temperature	230~260℃
$t_L$	Retention time for $T_L$	Within 40sec.
$T_P$	Peak temperature	260℃(Max)
$t_p$	Time for peak temperature	Within 10sec.
$\Delta T_R/\Delta t$	Temperature rising rate	Under 3℃/sec.
$\Delta T_D/\Delta t$	Temperature decreasing rate	Over -3℃/sec.



※Above conditions are for reference. Therefore, evaluate by customer's own circuit boards and reflow furnaces before using, because stress from circuit boards and temperature variations of reflow furnaces vary by customer's own conditions.

#### 4 – 7. Attention Points in Soldering Operation

This product was developed as a surface mount LED especially suitable for reflow soldering. So reflow soldering is recommended. In case of implementing manual soldering, please take care of following points.

##### ①SOLDER USED

Sn-Cu, Sn-Ag-Cu, Sn-Ag-Bi-Cu

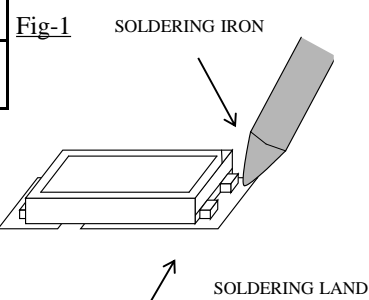
##### ②HAND SOLDERING CONDITION

LED products do not contain reinforcement material such as a glass fillers.

So thermal stress by soldering greatly influence its reliability.

Please keep following points for manual soldering.

	ITEM	RECOMMENDED CONDITION
a)	Heating method	Condition ) Temp. of iron top less than 325℃ within 3 sec. Heating on PCB pattern, not direct to the LED. (Fig-1)
b)	Handling after soldering	Please handle after the part temp. goes down to room temp.



#### 4 – 8. Cleaning after Soldering

Please follow the conditions below if the cleaning is necessary after soldering.

Solvent	We recommend to use alcohols solvent such as, isopropyl alcohols
Temperature	Under 30℃ within 3 minutes
Ultrasonic Cleaning	15W/ Below 1 liter (capacity of tank)
Drying	Under 100℃ within 3 minutes

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